

NTB5405N, NVB5405N

MOSFET – Power, Single, N-Channel, D²PAK 40 V, 116 A

Features

- Low $R_{DS(on)}$
- High Current Capability
- Low Gate Charge
- AEC-Q101 Qualified and PPAP Capable – NVB5405N
- These Devices are Pb-Free and are RoHS Compliant

Applications

- Electronic Brake Systems
- Electronic Power Steering
- Bridge Circuits

MAXIMUM RATINGS ($T_J = 25^\circ\text{C}$ unless otherwise stated)

Parameter		Symbol	Value	Unit	
Drain-to-Source Voltage		V_{DS}	40	V	
Gate-to-Source Voltage		V_{GS}	± 20	V	
Continuous Drain Current – $R_{\theta JC}$	Steady State	I_D	$T_C = 25^\circ\text{C}$	116	A
			$T_C = 100^\circ\text{C}$	82	
Power Dissipation – $R_{\theta JC}$	Steady State	P_D	150	W	
Continuous Drain Current – $R_{\theta JA}$ (Note 1)	Steady State	I_D	$T_A = 25^\circ\text{C}$	16.5	A
			$T_A = 100^\circ\text{C}$	11.6	
Power Dissipation – $R_{\theta JA}$ (Note 1)	Steady State	P_D	3.0	W	
Pulsed Drain Current	$t_p = 10 \mu\text{s}$	I_{DM}	280	A	
Operating Junction and Storage Temperature		T_J, T_{STG}	-55 to 175	$^\circ\text{C}$	
Source Current (Body Diode) Pulsed		I_S	75	A	
Single Pulse Drain-to-Source Avalanche Energy – ($V_{DD} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_{PK} = 40 \text{ A}, L = 1 \text{ mH}, R_G = 25 \Omega$)		EAS	800	mJ	
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)		T_L	260	$^\circ\text{C}$	

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL RESISTANCE RATINGS

Parameter	Symbol	Max	Unit
Junction-to-Case (Drain)	$R_{\theta JC}$	1.0	$^\circ\text{C}/\text{W}$
Junction-to-Ambient (Note 1)	$R_{\theta JA}$	50	$^\circ\text{C}/\text{W}$

1. Surface mounted on FR4 board using 1 sq in pad size, (Cu Area 1.127 sq in [2 oz] including traces).

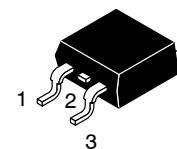
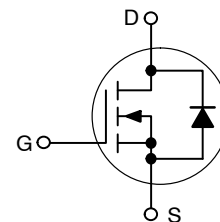


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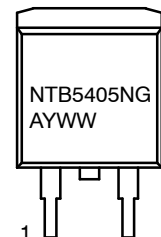
$V_{(BR)DSS}$	$R_{DS(ON)}$ TYP	I_D MAX (Note 1)
40 V	4.9 m Ω @ 10 V	116 A

N-Channel



D²PAK
CASE 418B
STYLE 2

MARKING DIAGRAM



NTB5405N = Specific Device Code
G = Pb-Free Device
A = Assembly Location
Y = Year
WW = Work Week

ORDERING INFORMATION

Device	Package	Shipping†
NTB5405NG	D ² PAK (Pb-Free)	50 Units / Rail
NTB5405NT4G	D ² PAK (Pb-Free)	800 / Tape & Reel
NVB5405NT4G	D ² PAK (Pb-Free)	800 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

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ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise stated)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = 250 μA	40			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /T _J			39		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V, V _{DS} = 40 V	T _J = 25°C		1.0	μA
			T _J = 100°C		10	
Gate-to-Source Leakage Current	I _{GSS}	V _{DS} = 0 V, V _{GS} = ±30 V			±100	nA

ON CHARACTERISTICS (Note 2)

Gate Threshold Voltage	V _{GS(TH)}	V _{GS} = V _{DS} , I _D = 250 μA	1.5		3.5	V
Gate Threshold Temperature Coefficient	V _{GS(TH)} /T _J			-7.0		mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 10 V, I _D = 40 A		4.9	5.8	mΩ
		V _{GS} = 5.0 V, I _D = 15 A		7.0	8.0	
Forward Transconductance	g _{FS}	V _{GS} = 10 V, I _D = 15 A		32		S

CHARGES AND CAPACITANCES

Input Capacitance	C _{ISS}	V _{GS} = 0 V, f = 1.0 MHz, V _{DS} = 32 V		2700	4000	pF
Output Capacitance	C _{OSS}			700	1400	
Reverse Transfer Capacitance	C _{RSS}			300	600	
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 10 V, V _{DS} = 32 V, I _D = 40 A		88		nC
Threshold Gate Charge	Q _{G(TH)}			3.25		
Gate-to-Source Charge	Q _{GS}			9.5		
Gate-to-Drain Charge	Q _{GD}			37		

SWITCHING CHARACTERISTICS, V_{GS} = 10 V (Note 3)

Turn-On Delay Time	t _{d(ON)}	V _{GS} = 10 V, V _{DD} = 32 V, I _D = 40 A, R _G = 2.5 Ω		8.5		ns
Rise Time	t _r			52		
Turn-Off Delay Time	t _{d(OFF)}			55		
Fall Time	t _f			70		

SWITCHING CHARACTERISTICS, V_{GS} = 5 V (Note 3)

Turn-On Delay Time	t _{d(ON)}	V _{GS} = 5 V, V _{DD} = 20 V, I _D = 20 A, R _G = 2.5 Ω		19		ns
Rise Time	t _r			153		
Turn-Off Delay Time	t _{d(OFF)}			32		
Fall Time	t _f			42		

DRAIN-SOURCE DIODE CHARACTERISTICS

Forward Diode Voltage	V _{SD}	V _{GS} = 0 V, I _S = 20 A	T _J = 25°C	0.82	1.1	V
			T _J = 100°C	TBD		
Reverse Recovery Time	t _{RR}	V _{GS} = 0 V, dI _{SD} /dt = 100 A/μs, I _S = 20 A		66		ns
Charge Time	t _a			35		
Discharge Time	t _b			31		
Reverse Recovery Charge	Q _{RR}			113		

- Pulse Test: pulse width ≤ 300 μs, duty cycle ≤ 2%.
- Switching characteristics are independent of operating junction temperatures.

TYPICAL PERFORMANCE CURVES

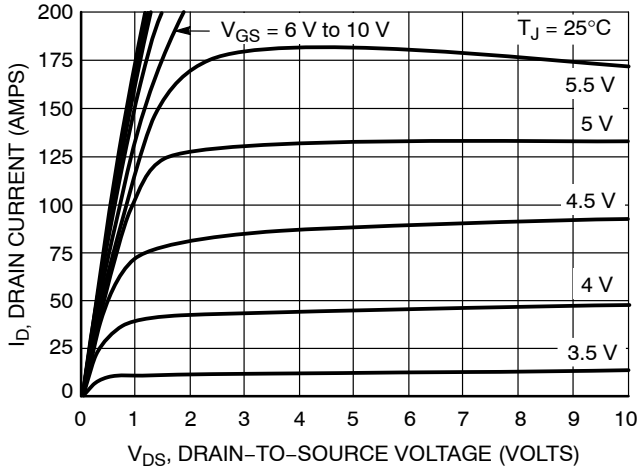


Figure 1. On-Region Characteristics

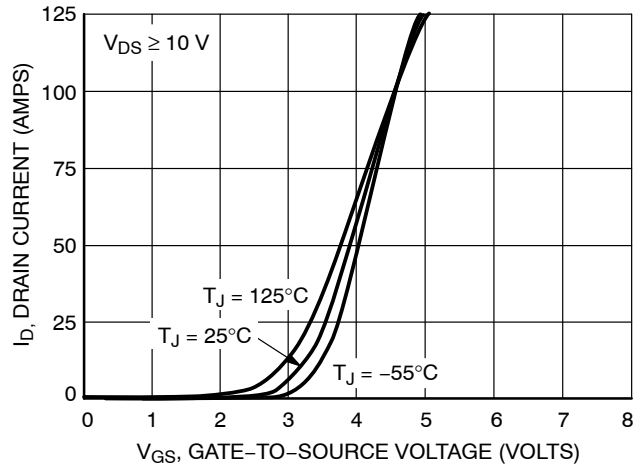


Figure 2. Transfer Characteristics

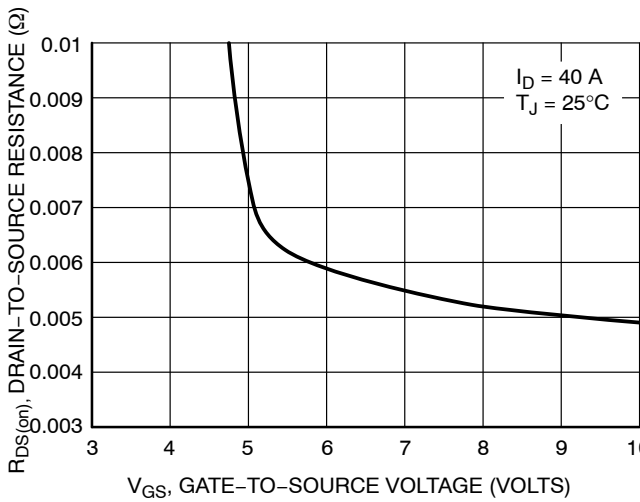


Figure 3. On-Resistance vs. Gate-to-Source Voltage

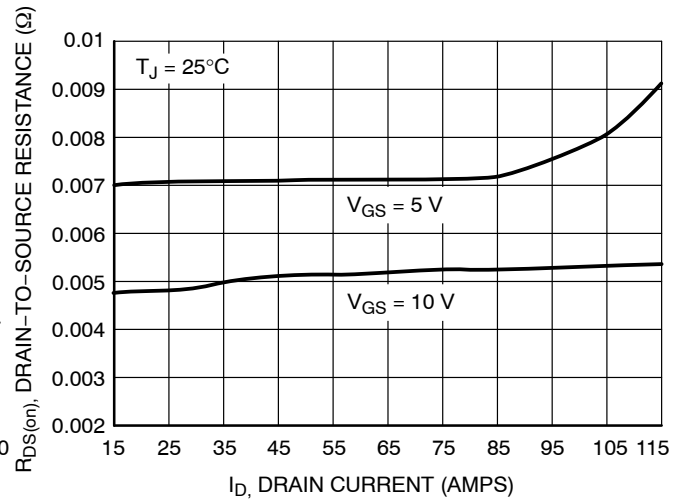


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

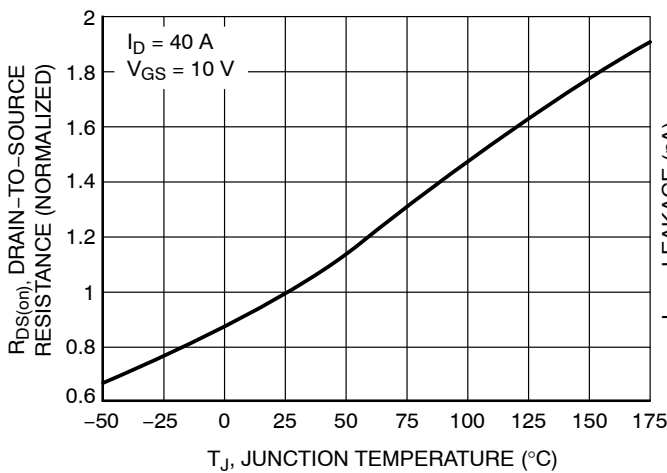


Figure 5. On-Resistance Variation with Temperature

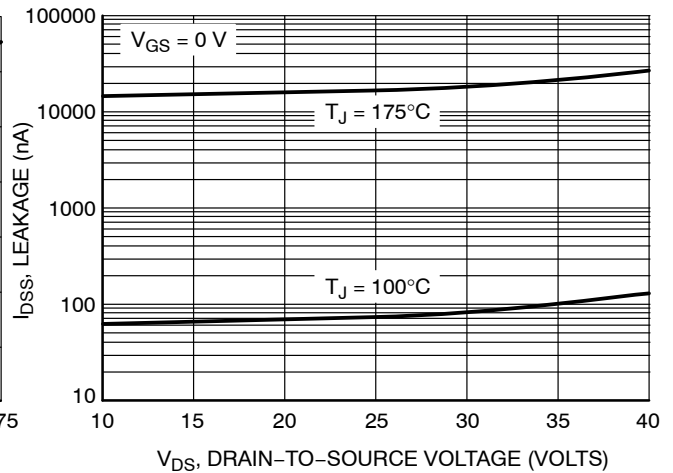


Figure 6. Drain-to-Source Leakage Current vs. Voltage

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TYPICAL PERFORMANCE CURVES

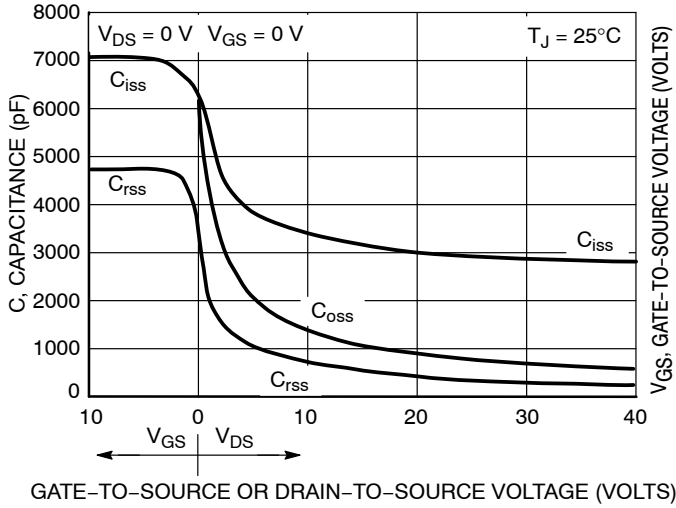


Figure 7. Capacitance Variation

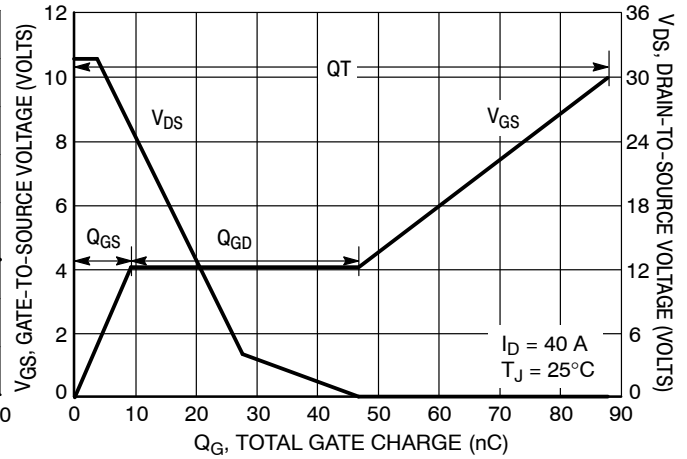


Figure 8. Gate-To-Source and Drain-To-Source Voltage vs. Total Charge

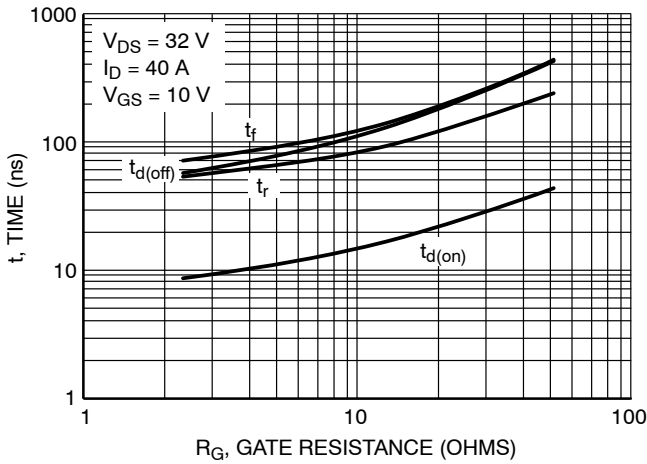


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

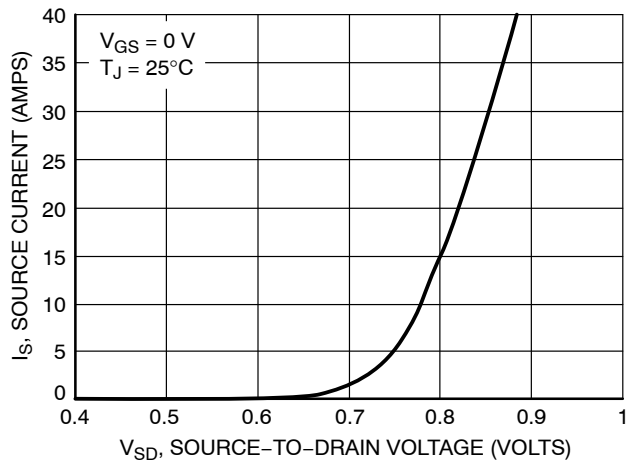


Figure 10. Diode Forward Voltage vs. Current

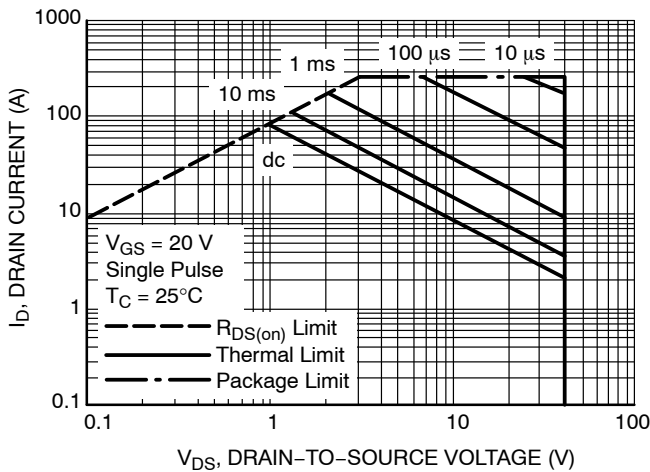


Figure 11. Maximum Rated Forward Biased Safe Operating Area

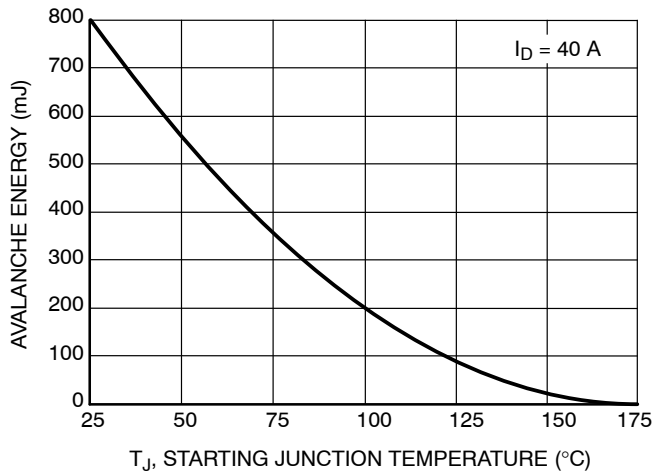


Figure 12. Maximum Avalanche Energy vs. Starting Junction Temperature

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TYPICAL PERFORMANCE CURVES

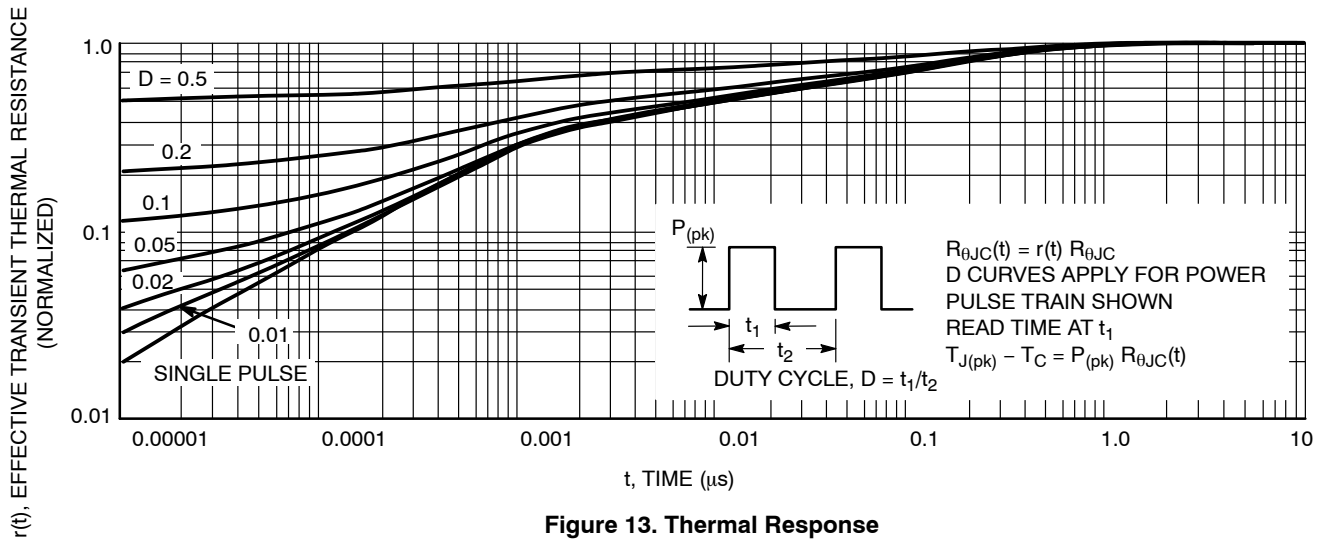


Figure 13. Thermal Response

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

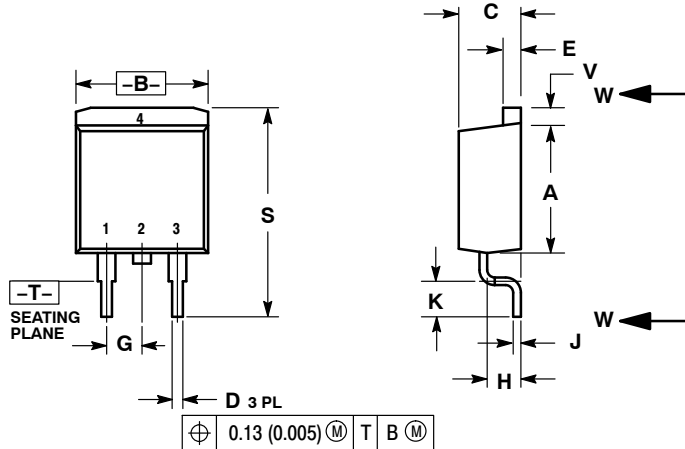
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D²PAK 3
CASE 418B-04
ISSUE L

DATE 17 FEB 2015

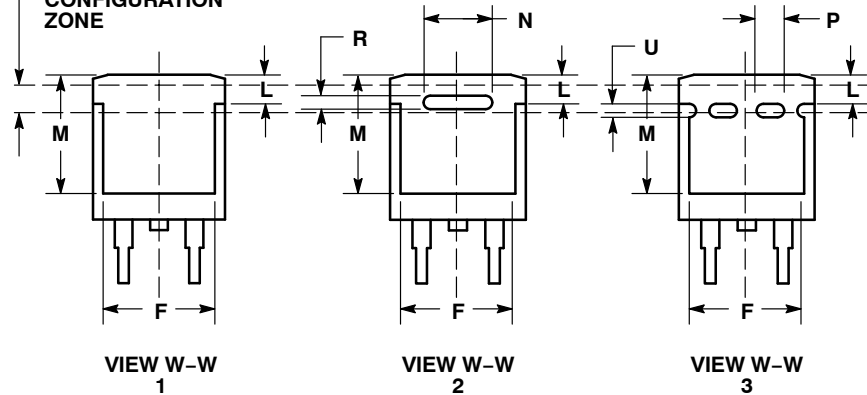
SCALE 1:1



- NOTES:
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 - CONTROLLING DIMENSION: INCH.
 - 418B-01 THRU 418B-03 OBSOLETE, NEW STANDARD 418B-04.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.340	0.380	8.64	9.65
B	0.380	0.405	9.65	10.29
C	0.160	0.190	4.06	4.83
D	0.020	0.035	0.51	0.89
E	0.045	0.055	1.14	1.40
F	0.310	0.350	7.87	8.89
G	0.100	BSC	2.54	BSC
H	0.080	0.110	2.03	2.79
J	0.018	0.025	0.46	0.64
K	0.090	0.110	2.29	2.79
L	0.052	0.072	1.32	1.83
M	0.280	0.320	7.11	8.13
N	0.197	REF	5.00	REF
P	0.079	REF	2.00	REF
R	0.039	REF	0.99	REF
S	0.575	0.625	14.60	15.88
V	0.045	0.055	1.14	1.40

VARIABLE CONFIGURATION ZONE



- | | | | | | |
|-----------------------------------------------------------------------|--------------------------------------------------------------|------------------------------------------------------------------|-----------------------------------------------------------------------|------------------------------------------------------------------|-----------------------------------------------------------------------|
| STYLE 1:
PIN 1. BASE
2. COLLECTOR
3. EMITTER
4. COLLECTOR | STYLE 2:
PIN 1. GATE
2. DRAIN
3. SOURCE
4. DRAIN | STYLE 3:
PIN 1. ANODE
2. CATHODE
3. ANODE
4. CATHODE | STYLE 4:
PIN 1. GATE
2. COLLECTOR
3. EMITTER
4. COLLECTOR | STYLE 5:
PIN 1. CATHODE
2. ANODE
3. CATHODE
4. ANODE | STYLE 6:
PIN 1. NO CONNECT
2. CATHODE
3. ANODE
4. CATHODE |
|-----------------------------------------------------------------------|--------------------------------------------------------------|------------------------------------------------------------------|-----------------------------------------------------------------------|------------------------------------------------------------------|-----------------------------------------------------------------------|

MARKING INFORMATION AND FOOTPRINT ON PAGE 2

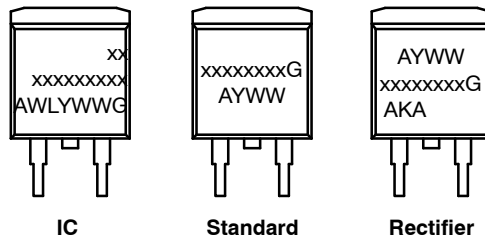
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CASE 418B-04
ISSUE L

DATE 17 FEB 2015

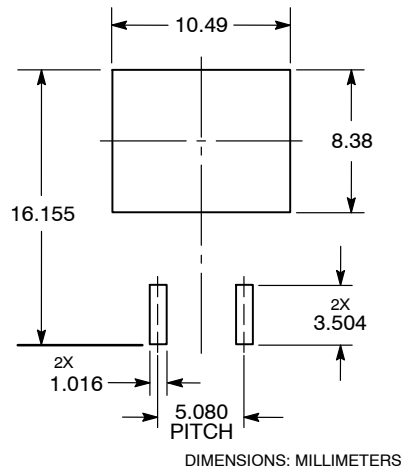
**GENERIC
MARKING DIAGRAM***



- xx = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- Y = Year
- WW = Work Week
- G = Pb-Free Package
- AKA = Polarity Indicator

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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